

NTE5332 & NTE5334 Silicon Bridge Rectifier, 1A

Features:

- Glass Passivated Chip Junctions
- Surge Overload Rating: 50A (Peak)
- Ideal for Printed Circuit Board
- High Temperature Soldering Guaranteed: +285°C/10 seconds at 5 lbs., (2.3kg) tension

Maximum Ratings and Electrical Characteristics: ($T_A = +25^\circ\text{C}$ unless otherwise specified, 60Hz, Resistive or Inductive Load.)

Maximum Recurrent Peak Reverse Voltage, V_{RRM}

NTE5332	600V
NTE5334	1000V

Maximum RMS, V_{RMS}

NTE5332	420V
NTE5334	700V

Maximum DC Blocking Voltage, V_{DC}

NTE5332	600V
NTE5334	1000V

Maximum Average Forward Output Rectified Current ($T_A = +40^\circ\text{C}$), $I_{O(AV)}$ 1A

Peak Forward Surge Current (Single Sine-Wave Superimposed on Rated Load), I_{FSM} 50A

Rating for Fusing ($t < 8.35\text{ms}$), I^2t $10\text{A}^2\text{s}$

Maximum Instantaneous Forward Voltage Drop (Per element at 1A), V_F 1.2V

Maximum Reverse Current at Rated DC Blocking Voltage Per Element, I_R

$T_A = +25^\circ\text{C}$	10 μA
$T_A = +125^\circ\text{C}$	500 μA

Typical Junction Capacitance Per Element (Note 1), C_J 25pf

Typical thermal Resistance (Note 2), $R_{\theta JA}$ $+40^\circ\text{C/W}$

Operating Junction Temperature Range, T_J -65° to $+150^\circ\text{C}$

Storage Temperature Range, T_{stg} -65° to $+150^\circ\text{C}$

Note 1. Measured at 1.0MHz and applied reverse voltage of 4.0 Volts.

Note 2. Thermal Resistance from Junction to Ambient mounted on P.C. Board with 0.5" x 0.5" (13mm x 13mm) Copper Pads.

